



November 2015

# FCH125N60E

## N-Channel SuperFET<sup>®</sup> II Easy-Drive MOSFET

600 V, 29 A, 125 mΩ

### Features

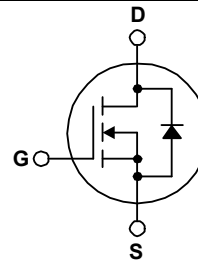
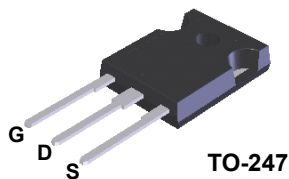
- 650 V @T<sub>J</sub> = 150°C
- Typ. R<sub>DS(on)</sub> = 102 mΩ
- Ultra Low Gate Charge (Typ. Q<sub>g</sub> = 75 nC)
- Low Effective Output Capacitance (Typ. C<sub>oss(eff)</sub> = 258 pF)
- 100% Avalanche Tested
- RoHS Compliant

### Applications

- Telecom / Server Power Supplies
- Industrial Power Supplies

### Description

SuperFET<sup>®</sup> II MOSFET is Fairchild Semiconductor's brand-new high voltage super-junction (SJ) MOSFET family that is utilizing charge balance technology for outstanding low on-resistance and lower gate charge performance. This technology is tailored to minimize conduction loss, provide superior switching performance, dv/dt rate and higher avalanche energy. Consequently, SuperFET II MOSFET easy-drive series offers slightly slower rise and fall times compared to the SuperFET II MOSFET series. Noted by the "E" part number suffix, this family helps manage EMI issues and allows for easier design implementation. For faster switching in applications where switching losses must be at an absolute minimum, please consider the SuperFET II MOSFET series.



### Absolute Maximum Ratings T<sub>C</sub> = 25°C unless otherwise noted.

Symbol	Parameter	FCH125N60E	Unit
V <sub>DSS</sub>	Drain to Source Voltage	600	V
V <sub>GSS</sub>	Gate to Source Voltage	- DC	±20
		- AC (f > 1 Hz)	±30
I <sub>D</sub>	Drain Current	- Continuous (T <sub>C</sub> = 25°C)	29
		- Continuous (T <sub>C</sub> = 100°C)	18
I <sub>DM</sub>	Drain Current - Pulsed (Note 1)	87	A
E <sub>AS</sub>	Single Pulsed Avalanche Energy (Note 2)	720	mJ
I <sub>AR</sub>	Avalanche Current (Note 1)	6	A
E <sub>AR</sub>	Repetitive Avalanche Energy (Note 1)	2.78	mJ
dv/dt	MOSFET dv/dt	100	V/ns
	Peak Diode Recovery dv/dt (Note 3)	20	
P <sub>D</sub>	Power Dissipation	(T <sub>C</sub> = 25°C)	278
		- Derate Above 25°C	2.2
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Temperature Range	-55 to +150	°C
T <sub>L</sub>	Maximum Lead Temperature for Soldering, 1/8" from Case for 5 Seconds	300	°C

### Thermal Characteristics

Symbol	Parameter	FCH125N60E	Unit
R <sub>θJC</sub>	Thermal Resistance, Junction to Case, Max.	0.45	°C/W
R <sub>θJA</sub>	Thermal Resistance, Junction to Ambient, Max.	40	

## Package Marking and Ordering Information

Part Number	Top Mark	Package	Packing Method	Reel Size	Tape Width	Quantity
FCH125N60E	FCH125N60E	TO-247	Tube	N/A	N/A	30 units

## Electrical Characteristics $T_C = 25^\circ\text{C}$ unless otherwise noted.

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
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### Off Characteristics

$BV_{DSS}$	Drain to Source Breakdown Voltage	$V_{GS} = 0\text{ V}, I_D = 10\text{ mA}, T_J = 25^\circ\text{C}$	600	-	-	V
		$V_{GS} = 0\text{ V}, I_D = 10\text{ mA}, T_J = 150^\circ\text{C}$	650	-	-	V
$\Delta BV_{DSS} / \Delta T_J$	Breakdown Voltage Temperature Coefficient	$I_D = 10\text{ mA}$ , Referenced to $25^\circ\text{C}$	-	0.7	-	$\text{V}/^\circ\text{C}$
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS} = 600\text{ V}, V_{GS} = 0\text{ V}$	-	-	1	$\mu\text{A}$
		$V_{DS} = 480\text{ V}, V_{GS} = 0\text{ V}, T_C = 125^\circ\text{C}$	-	2	-	
$I_{GSS}$	Gate to Body Leakage Current	$V_{GS} = \pm 20\text{ V}, V_{DS} = 0\text{ V}$	-	-	$\pm 100$	nA

### On Characteristics

$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS} = V_{DS}, I_D = 250\text{ }\mu\text{A}$	2.5	-	3.5	V
$R_{DS(on)}$	Static Drain to Source On Resistance	$V_{GS} = 10\text{ V}, I_D = 14.5\text{ A}$	-	102	125	$\text{m}\Omega$
$g_{FS}$	Forward Transconductance	$V_{DS} = 20\text{ V}, I_D = 14.5\text{ A}$	-	25	-	S

### Dynamic Characteristics

$C_{iss}$	Input Capacitance	$V_{DS} = 380\text{ V}, V_{GS} = 0\text{ V}, f = 1\text{ MHz}$	-	2250	2990	pF
$C_{oss}$	Output Capacitance		-	60	80	pF
$C_{rSS}$	Reverse Transfer Capacitance		-	17	-	pF
$C_{oss(eff.)}$	Effective Output Capacitance	$V_{DS} = 0\text{ V to } 480\text{ V}, V_{GS} = 0\text{ V}$	-	258	-	pF
$Q_{g(tot)}$	Total Gate Charge at 10V	$V_{DS} = 380\text{ V}, I_D = 14.5\text{ A}, V_{GS} = 10\text{ V}$	-	75	95	nC
$Q_{gs}$	Gate to Source Gate Charge		-	10	-	nC
$Q_{gd}$	Gate to Drain "Miller" Charge		(Note 4)	-	33	-
ESR	Equivalent Series Resistance	$f = 1\text{ MHz}$	-	3.5	-	$\Omega$

### Switching Characteristics

$t_{d(on)}$	Turn-On Delay Time	$V_{DD} = 380\text{ V}, I_D = 14.5\text{ A}, V_{GS} = 10\text{ V}, R_g = 4.7\text{ }\Omega$	-	23	56	ns
$t_r$	Turn-On Rise Time		-	20	50	ns
$t_{d(off)}$	Turn-Off Delay Time		-	106	222	ns
$t_f$	Turn-Off Fall Time		(Note 4)	-	23	56

### Drain-Source Diode Characteristics

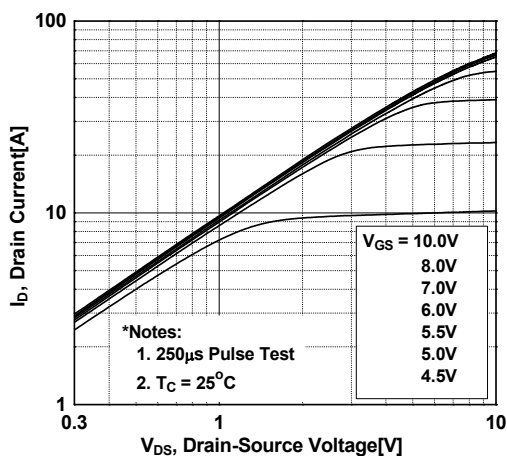
$I_S$	Maximum Continuous Drain to Source Diode Forward Current	-	-	29	A	
$I_{SM}$	Maximum Pulsed Drain to Source Diode Forward Current	-	-	87	A	
$V_{SD}$	Drain to Source Diode Forward Voltage	$V_{GS} = 0\text{ V}, I_{SD} = 14.5\text{ A}$	-	-	1.2	V
$t_{rr}$	Reverse Recovery Time	$V_{GS} = 0\text{ V}, I_{SD} = 14.5\text{ A}, di_F/dt = 100\text{ A}/\mu\text{s}$	-	376	-	ns
$Q_{rr}$	Reverse Recovery Charge		-	6.5	-	$\mu\text{C}$

#### Notes:

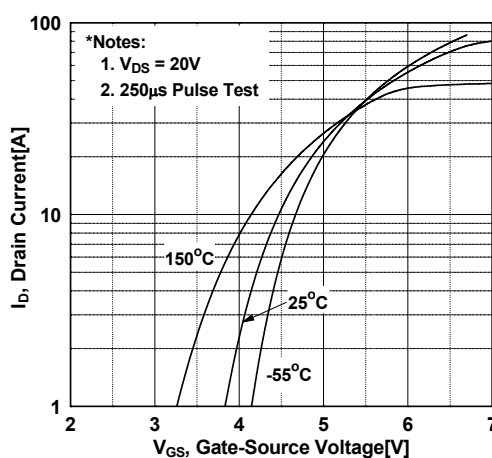
1. Repetitive rating: pulse width limited by maximum junction temperature.
2.  $I_{AS} = 6.0\text{ A}, R_G = 25\text{ }\Omega$ , Starting  $T_J = 25^\circ\text{C}$
3.  $I_{SD} \leq 14.5\text{ A}, di/dt \leq 200\text{ A}/\mu\text{s}, V_{DD} \leq 380\text{ V}$ , Starting  $T_J = 25^\circ\text{C}$
4. Essentially independent of operating temperature.

## Typical Performance Characteristics

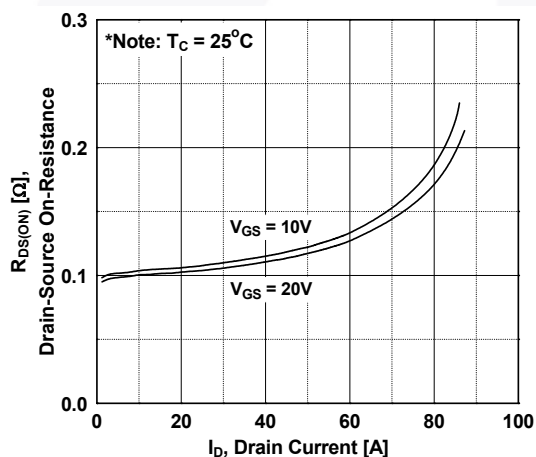
**Figure 1. On-Region Characteristics**



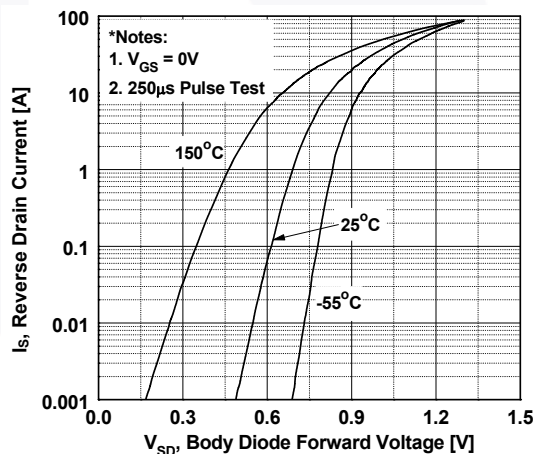
**Figure 2. Transfer Characteristics**



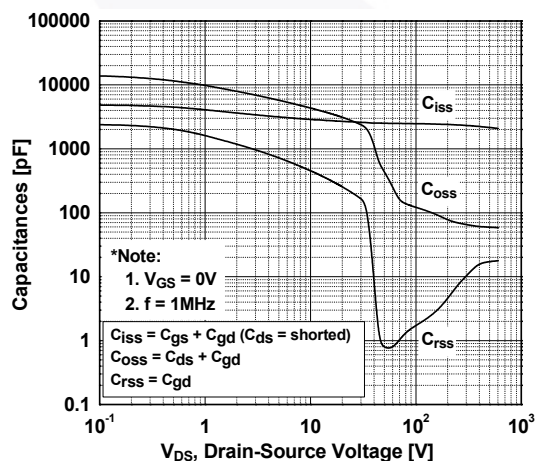
**Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage**



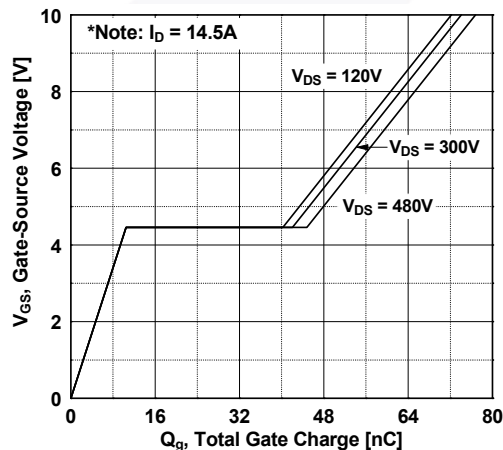
**Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature**



**Figure 5. Capacitance Characteristics**

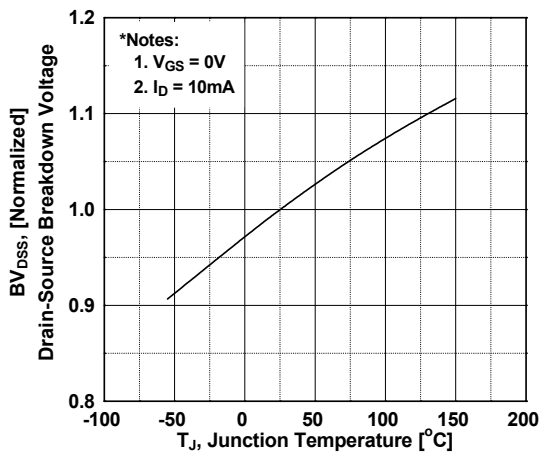


**Figure 6. Gate Charge Characteristics**

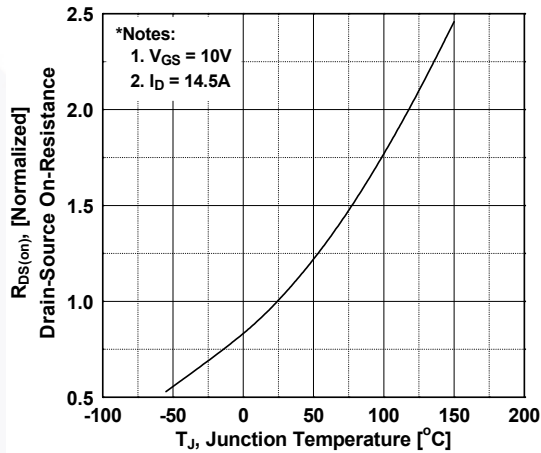


**Typical Performance Characteristics** (Continued)

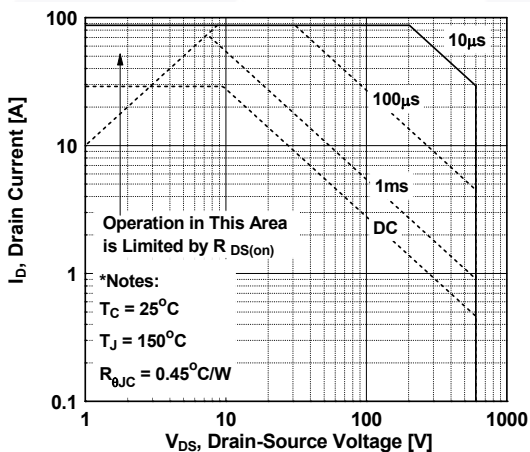
**Figure 7. Breakdown Voltage Variation vs. Temperature**



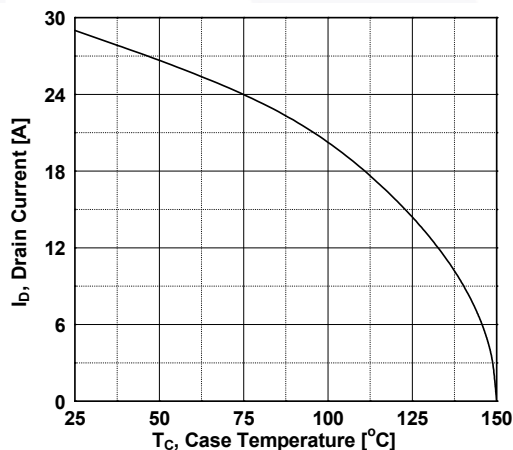
**Figure 8. On-Resistance Variation vs. Temperature**



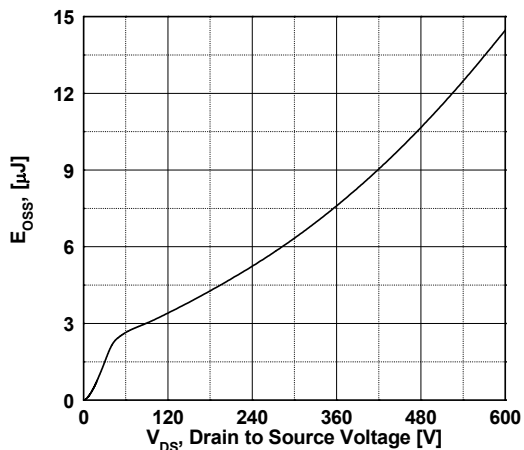
**Figure 9. Maximum Safe Operating Area**



**Figure 10. Maximum Drain Current vs. Case Temperature**

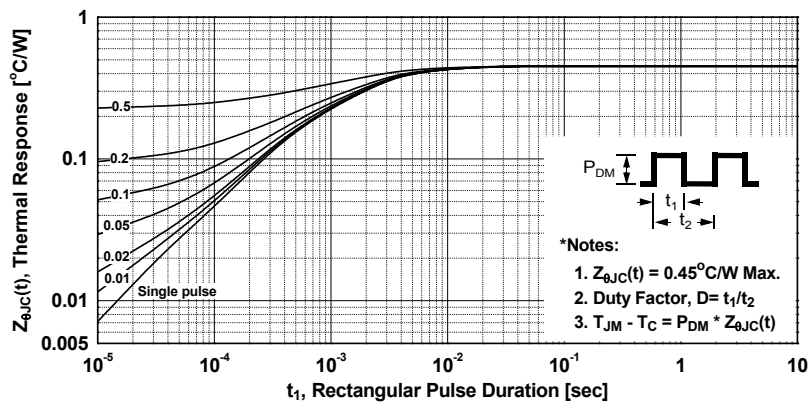


**Figure 11. Eoss vs. Drain to Source Voltage**



Typical Performance Characteristics (Continued)

Figure 12. Transient Thermal Response Curve



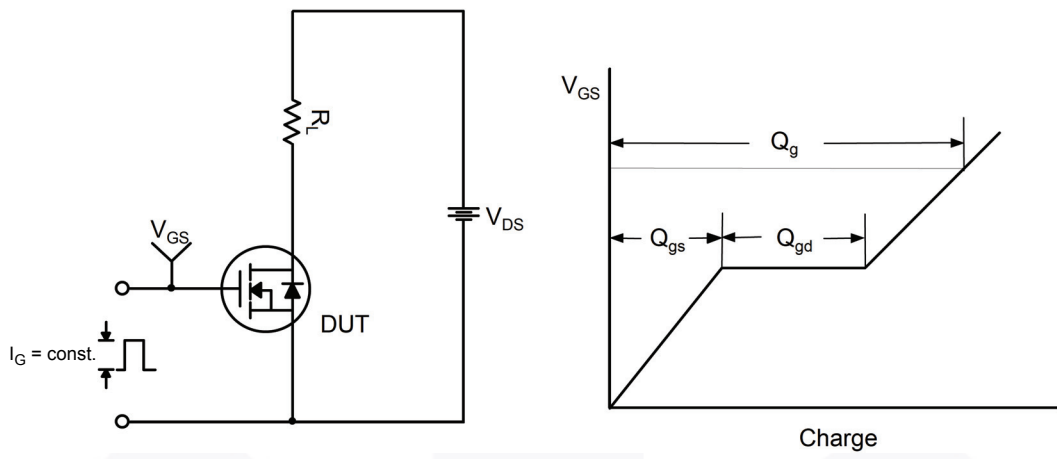


Figure 13. Gate Charge Test Circuit & Waveform

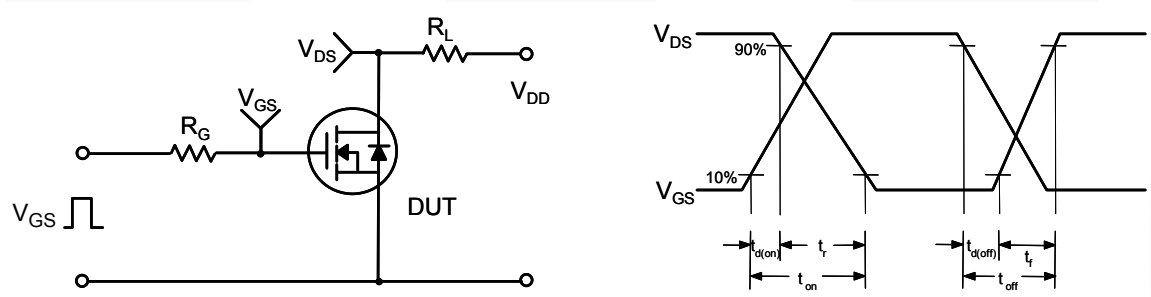


Figure 14. Resistive Switching Test Circuit & Waveforms

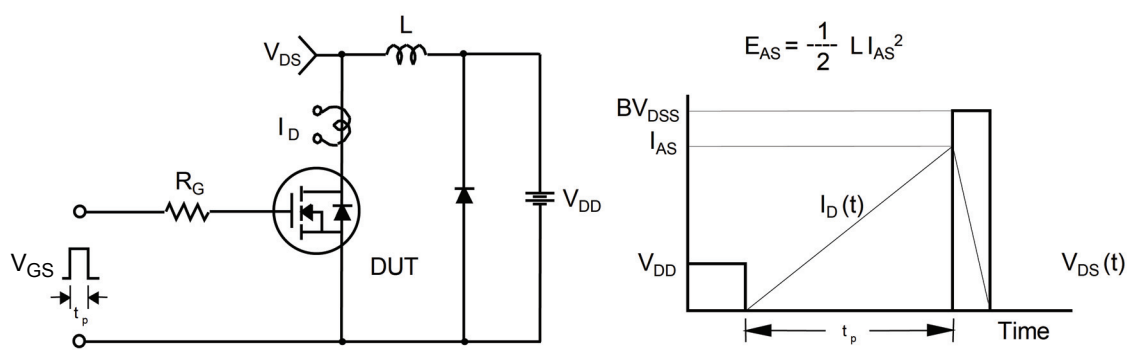


Figure 15. Unclamped Inductive Switching Test Circuit & Waveforms

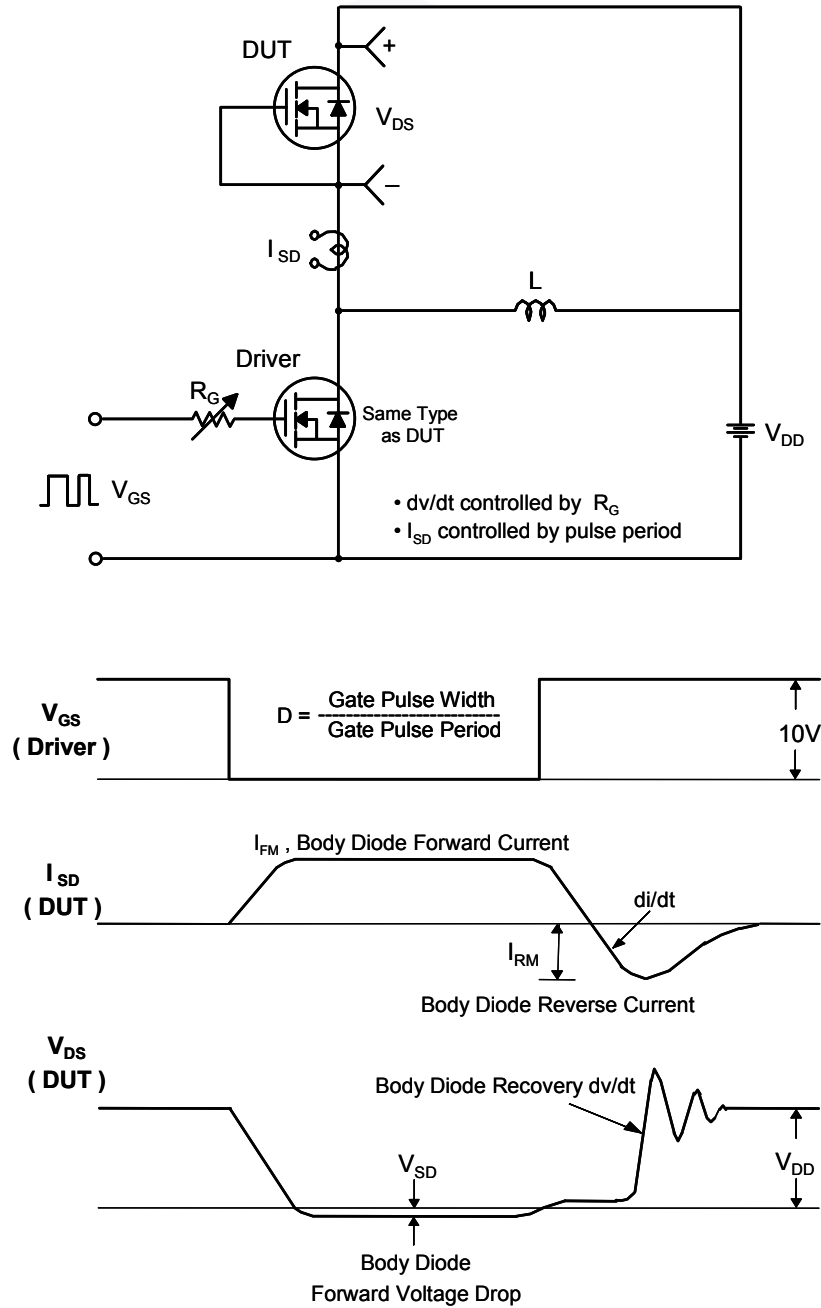
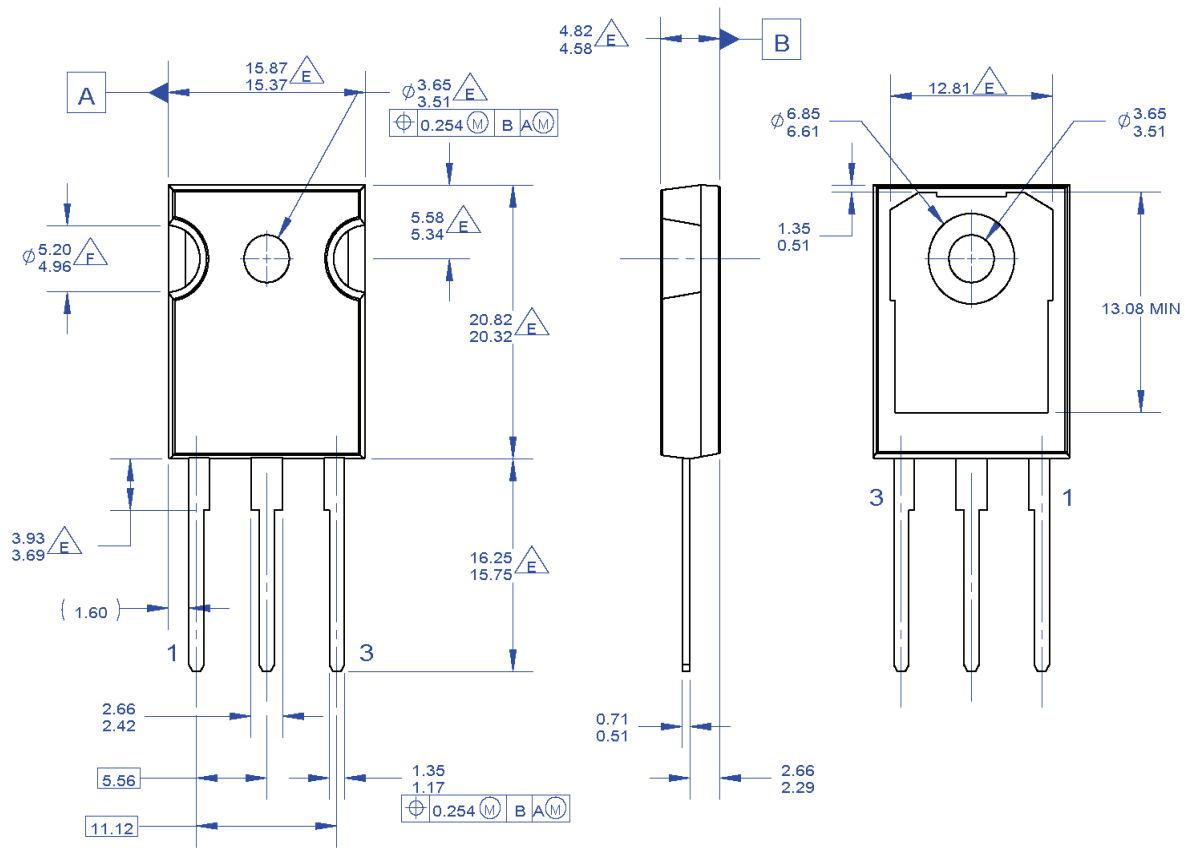


Figure 16. Peak Diode Recovery  $dv/dt$  Test Circuit & Waveforms

## Mechanical Dimensions



NOTES: UNLESS OTHERWISE SPECIFIED.

- A. PACKAGE REFERENCE: JEDEC TO-247, ISSUE E, VARIATION AB, DATED JUNE, 2004.
- B. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.
- C. ALL DIMENSIONS ARE IN MILLIMETERS.
- D. DRAWING CONFORMS TO ASME Y14.5 - 1994
- DOES NOT COMPLY JEDEC STANDARD VALUE
- NOTCH MAY BE SQUARE
- G. DRAWING FILENAME: MKT-TO247A03\_REV03

**Figure 17. TO-247, Molded, 3-Lead, Jedec Variation AB**

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| AttitudeEngine™  | FRFET®  |  ® |  SYSTEM GENERAL® |
| Awinda®*   | Global Power Resource™                          | Power Supply WebDesigner™   | TinyBoost®  |
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| CROSSVOLT™   | IntelliMAX™                                     | Quiet Series™   | TinyPWM™  |
| CTL™   | ISOPLANAR™                                      | RapidConfigure™   | TinyWire™   |
| Current Transfer Logic™  | Marking Small Speakers Sound Louder and Better™ |  ™ | TranSiC™  |
| DEUXPEED®  | MegaBuck™                                       | Saving our world, 1mW/W/kW at a time™   | TriFault Detect™  |
| Dual Cool™   | MICROCOUPLER™                                   | SignalWise™   | TRUECURRENT®*   |
| EcoSPARK®  | MicroFET™                                       | SmartMax™   | μSerDes™  |
| EfficientMax™  | MicroPak™                                       | SMART START™  |  SerDes™         |
| ESBC™  | MicroPak2™                                      | Solutions for Your Success™   | UHC®  |
|  Fairchild® | MillerDrive™                                    | SPM®  | Ultra FRFET™  |
| Fairchild Semiconductor®   | MotionMax™                                      | STEALTH™  | UniFET™   |
| FACT Quiet Series™   | MotionGrid®                                     | SuperFET®   | VCX™  |
| FACT®  | MTI®  | SuperSOT™-3   | VisualMax™  |
| FastvCore™   | MTx®  | SuperSOT™-6   | VoltagePlus™  |
| FETBench™  | MVN®  | SuperSOT™-8   | XS™   |
| FPS™   | mWSaver®  | SupreMOS®   | Xsens™  |
|  | OptoHiT™  | SyncFET™  | 仙童®   |
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No Identification Needed	Full Production	Datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve the design.
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